In the Specification:

Replace the paragraph on page 11, lines 13-23, with --

Fig. 2 shows, likewise schematically, an integrated electrical semiconductor circuit component (chip) 25 having two test contact points (test pads; test balls) 26 and 27 which form external test connecting contact points, via which the signals from other contact points (pads; balls) 28, which are not accessible after installation, in a BGA package can be monitored. As shown in three different views in figures 4a, 4b and 4c, the contact points 28 to the system board 29 are not accessible, since the contact points 28 are located on the lower face of the ~~package~~ housing 30, and are thus concealed between the housing 30 and the system board 29. --

Replace the two paragraphs on page 12, line 15, through page 13, line 8, with --

Fig. 3 shows a schematic view of integrated semiconductor circuit components 36 and 37 which are each mounted in a BGA package in an overall system, which is fitted on a customer-specific system board 38. Two metallic test points 39 and 40 are fitted on the system board 38, and are electrically connected to the two external accessible test contact points 26 and 27. The signals from the two balls, which are defined as external test contact points 26 and 27, in the integrated

semiconductor circuit component 36 can be seen at the two test points 39 and 40 on the system board 38.

The signals from all the other contact points 28 in the integrated circuit component 36 can be seen at these two external test contact points 26 and 27, and thus at the test points 39 and 40. The process of selectively passing on the individual signals in a controlled manner from all the contact points 28 to the external test contact points 26 and 27, respectively, is carried out, as shown in figure 1, by means of the multiplexing circuit 31. --